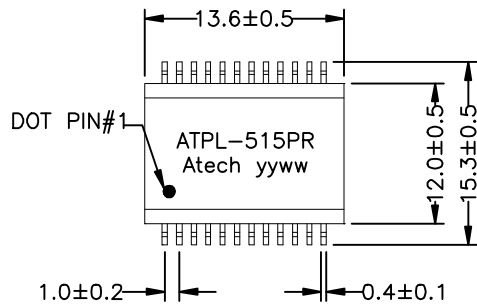
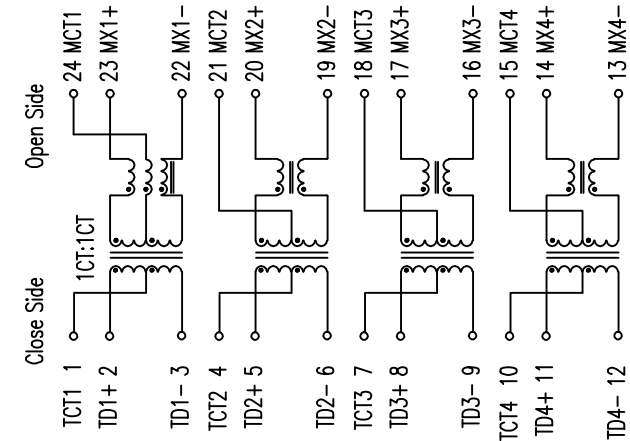


SUGGESTED PAD LAYOUT



* RoHS COMPLIANT

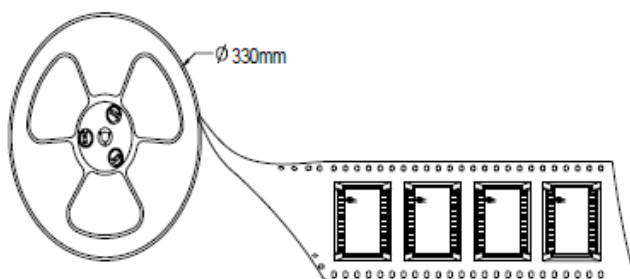
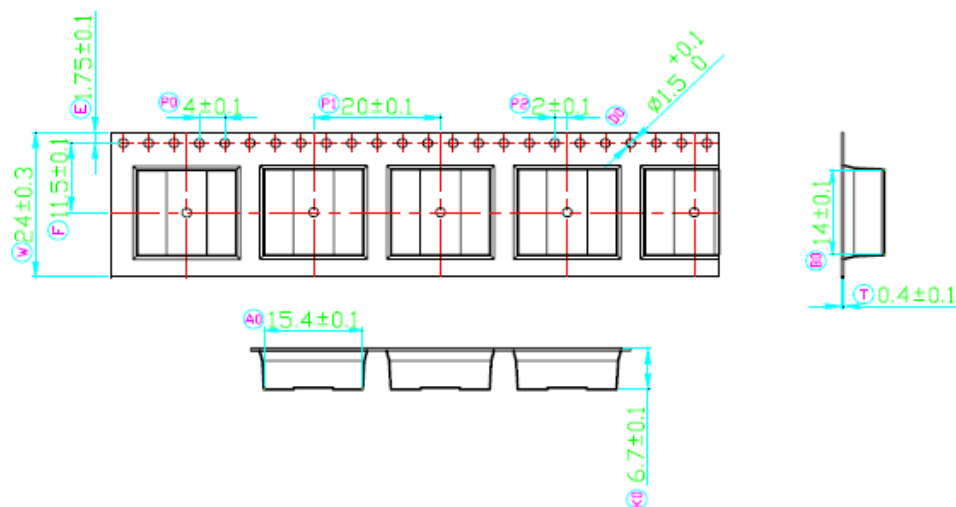
ELECTRICAL CHARACTERISTICS @25°C :

- INSULATION HI-POT : 1500 Vrms/0.5mA ,60Sec.
- TURN RATIO (±5%) : 1CT : 1CT
- OCL : : (@100kHz, 0.1Vrms, 8mA DC Bias) : 120uH MIN.
- CROSS TALK (dB MIN.) : 1-500MHz : -25
- INSERTION LOSS : 0.1-1MHz : -3.0dB MAX. 1-200MHz : -1.2dB MAX.
200-300MHz : -1.5dB MAX. 300-400MHz : -2.0dB MAX.
400-500MHz : -3.0dB MAX.
- RETURN LOSS : 0.3-100MHz : -18dB MIN. 100-200MHz : -16dB MIN.
200-300MHz : -12dB MIN. 300-400MHz : -10dB MIN.
400-500MHz : -8dB MIN.
- DIFFERENTIAL TO COMMON MODE REJECTION (dB MIN.) : 1-500MHz : -22
- LK(100kHz, 0.1Vrms) : 0.5uH MAX.
- Cw/w (100kHz, 0.1Vrms) : 25pF TYP.
- DCR : 0.9Ω TYP.
- OPERATING TEMPERATURE RANGE : 0°C~+70°C

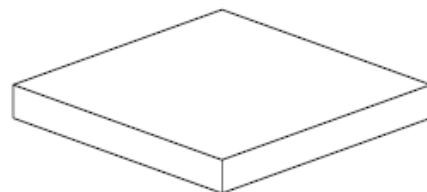
IEEE802.3 PoE+ COMPLIANT PERFORMANCE

							TITLE 10G BASE-T PoE+ TRANSFORMER	
							DWG. NO. ATPL-515PR	
	RELEASE	01/19 /2018	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	SHEET 1 OF 1
REVISIONS						01/19/18	DRAW SHIRLEY	

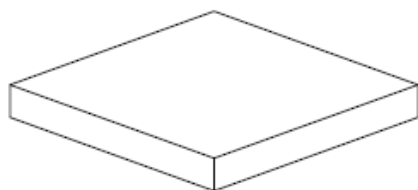
Package :



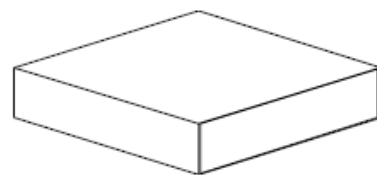
Two reel



Inner Carton



Five Inner Carton



Export Carton

Package Quantity:

One Reel=400Pcs

One Inner Carton=400*3=1200Pcs

One Export Carton=1200*2=2400Pcs

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tmin) Temperature Min (Tsmax) Time (Tmin to Tsmax) (ts)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (TL) Time (tL)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max